

## TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1 (CURRENTLY AMENDED): An encapsulation composition comprising one or more base oligomer/polymers; one or more diacrylate monomers selected from the group consisting of tricyclodecane dimethanol diacrylate, hydroxypivalaldehyde modified trimethylolpropane diacrylate and mixtures thereof; and one or more thixotropic agents; and one or more filler materials selected from the group consisting of spherical hollow glass beads, solid glass beads, talc, spherical silica and mixtures thereof.

2 - 4 (CANCELED)

5 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, wherein the diacrylate monomer is tricyclodecane dimethanol diacrylate.

6 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, wherein the one or more base oligomer/polymers is an acrylated/methacrylated or vinylene-containing oligomer/polymer.

7 (ORIGINAL): The encapsulation composition of claim 1, wherein the thixotropic agent is treated silica.

8 (CANCELED)

9 (CANCELED)

10 (CANCELED)

11 -12 (CANCELED)

13 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, further comprising a silane coupling agent.

14 (ORIGINAL): The encapsulation composition of claim 1, wherein the one or more base oligomer/polymers comprises in the range of about 1 to about 75 weight percent of the composition.

15 (ORIGINAL): The encapsulation composition of claim 14, wherein the one or more base oligomer/polymers comprises in the range of about 20 to about 50 weight percent of the composition.

16 (PREVIOUSLY AMENDED): The encapsulation composition of claim 1, wherein the one or more diacrylate monomers comprise in the range of about 1 to about 50 weight percent of the composition.

17 (PREVIOUSLY AMENDED): The encapsulation composition of claim 16, wherein the one or more diacrylate monomers comprise in the range of about 10 to about 30 weight percent of the composition.

18 (ORIGINAL): The encapsulation composition of claim 1, wherein the thixotropic agent comprises in the range of about 0.1 to about 8 weight percent of the composition.

19 (ORIGINAL): The encapsulation composition of claim 18, wherein the thixotropic agent comprises in the range of about 2 to about 5 weight percent of the composition.

20 (CANCELED)

21 (CURRENTLY AMENDED): The encapsulation composition of claim 19, wherein the one or more filler materials comprise in the range of about 1 to about 85 weight percent of the composition.

22 (ORIGINAL): The encapsulation composition of claim 21, wherein the one or more filler materials comprise in the range of about 50 to about 75 weight percent of the composition.

23 -26 (CANCELED)

27 (ORIGINAL): A method of providing encapsulation on an electronic component comprising the step of applying the composition of claim 1 to an electronic component.